



**EECS 143  
Microfabrication  
Technology**

Department of Electrical Engineering and  
Computer Sciences  
University of California, Berkeley

**Week #4 Quiz--Gate Oxidation**

Name \_\_\_\_\_ Section \_\_\_\_ Date \_\_\_\_\_

- (1) What is the purpose of the furnace tube TCA step?
- (2) Why do we run an additional "control" wafer during the oxidation?
- (3) How fast is the wafer boat pushed into and pulled out of the furnace?
- (4) Why is this push/pull rate important?
- (5) Are we performing a wet or dry oxidation? Why?
- (6) Why do we do an anneal step after oxidation?
- (7) What do we use the NanoSpec for, and how does it work (briefly)?
- (7) What do we use the Four-Point Probe for, and how does it work (briefly)?

M. Freed 1/20/99